SLLS225A - MARCH 1996 - REVISED FEBRUARY 1998

- Integrated Asynchronous Communications Element (ACE) Compatible With PCMCIA PC Card Standard Release 2.01
- Consists of a Single TL16C550 ACE Plus PCMCIA Interface Logic
- Provides Common I-Bus/Z-Bus Microcontroller Inputs for Most Intel<sup>™</sup> and Zilog<sup>™</sup> Subsystems
- Fully Programmable 256-Byte Card Information Structure (CIS) and 8-Byte Card Configuration Register (CCR)
- Adds or Deletes Standard Asynchronous Communication Bits (Start, Stop and Parity) to or From Serial Data Stream
- Independently Controlled Transmit, Receive, Line Status, and Data Set Interrupts
- Subsystem Selectable Serial-Bypass Mode Provides Subsystem With Direct Parallel Access to the FIFOs

- Fully Programmable Serial-Interface Characteristics:
  - 5-, 6-, 7-, or 8-Bit Characters
  - Even-, Odd-, or No-Parity Bit Generation and Detection
  - 1-, 1 1/2-, or 2-Stop Bit Generation
  - Baud-Rate Generation
- Fully Prioritized Interrupt System Controls
- Modem Control Functions
- Provides TL16C450 Mode at Reset Plus Selectable Normal TL16C550 Operation or Extended 64-Byte FIFO Mode
- Selectable Auto-RTS Mode Deactivates RTS at 14 Bytes in 550 Mode and at 56 Bytes in Extended 550 Mode
- Selectable Auto-CTS Mode Deactivates
   Serial Transfers When CTS is Inactive
- Available in 100 Pin Thin Quad Flatpack (PZ) Package

### description

The TL16PC564B/BLV<sup>†</sup> is designed to provide all the functions necessary for a Personal Computer Memory Card International Association (PCMCIA) universal asynchronous receiver transmitter (UART) subsystem interface. This interface provides a serial-to-parallel conversion for data to and from a modem coder-decoder/digital signal processor (CODEC/DSP) function to a PCMCIA parallel data-port format. A computer central processing unit (CPU), through a PCMCIA host controller, can read the status of the asynchronous communications element (ACE) interface at any point in the operation. Reported status information includes the type of transfer operation in process, the status of the operation, and any error conditions encountered.

Attribute memory consists of a 256-byte card information structure (CIS) and eight 8-byte card configuration registers (CCR). The CIS, implemented with a dual-port random-access memory (DPRAM), is available to both the host CPU and subsystem (modem), as are the CCRs. This DPRAM is used in place of the electrically erasable programmable read-only memory (EEPROM) normally used for the CIS. At power up, attribute memory is initialized by the subsystem.

The TL16PC564B/BLV uses a TL16C550 ACE-type core with an expanded  $64 \times 11$  receiver first-in-first-out (FIFO) memory and a  $64 \times 8$  transmitter FIFO memory. The receiver trigger logic flags have been adjusted in order to take full advantage of the increased capacity when in the extended mode. In addition, eight of the UART registers have been mapped into the subsystem (modem) memory space as read-only registers. This allows the subsystem to read UART status information.

A subsystem-selectable serial-bypass mode has been implemented to allow the subsystem to bypass the serial portion of the UART and write directly to the receiver FIFO and read directly from the transmitter FIFO. Interrupt operation is not affected in this mode.



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

Intel is a registered trademark of Intel System, Inc. Zilog is a registered trademark of Zilog Incorporated

† Patent pending



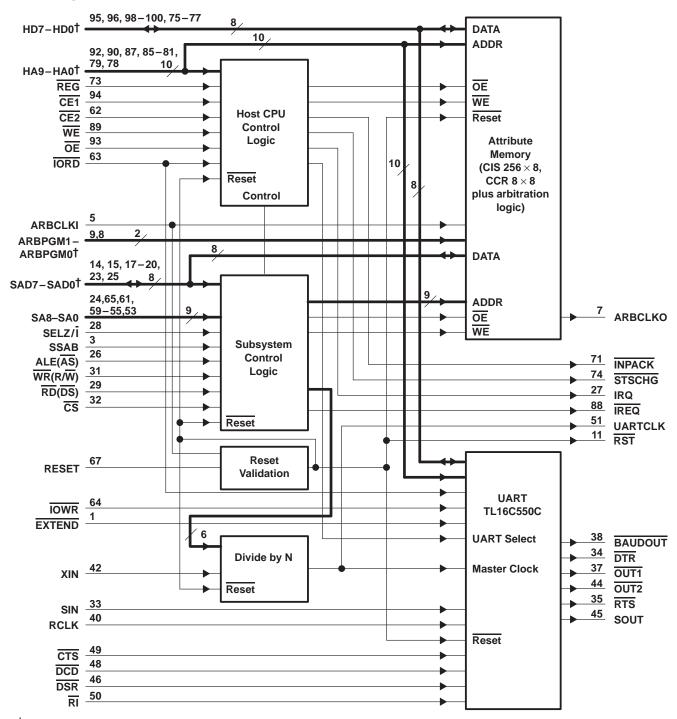
#### (TOP VIEW) HD3 HD4 HD6 HD6 HD7 HD7 HD8 HD8 HD9 HD9 HD0 HD0 HD0 $\begin{array}{c} 0.0 \\$ **EXTEND** ] HD2 75 VTEST □ □ STSCHG 2 74 3 SSAB [ REG 73 GND [ □ Vcc 72 ARBCLKI 🗆 □ INPACK 71 GND □ ☐ TESTOUT 70 ARBCLKO □ 69 ARBPGM0 ☐ □ GND 68 RESET ARBPGM1 ☐ 67 V<sub>CC</sub> □ RST □ 66 🗀 GND 65 🗀 SA7 11 NANDOUT [ 12 64 D TOWR GND □ 13 63 DIORD SAD7 14 62 🗆 CE2 SAD6 □ 15 □ SA6 61 60 VCC GND 🗆 16 SAD5 17 59 □ SA5 SAD4 □ □ SA4 18 58 SAD3 □ SA3 19 57 SAD2 20 56 □ SA2 V<sub>CC</sub> □ 21 55 □ SA1 V<sub>CC</sub> □ 22 □ GND 54 SAD1 🗆 23 □ SA0 53 52 VCC SA8 24 UARTCLK SAD0 [ 25 51 SELZ/Ī RD(DS)† GND (R/W) ALE (

**PZ PACKAGE** 



<sup>†</sup> The terminal names not enclosed in parentheses correspond to an Intel microcontroller signal, and the terminal names enclosed in parentheses correspond to a Zilog microcontroller signal.

### block diagram



<sup>†</sup> Bit 0 is the least significant bit.

### **Terminal Functions**

TERMINAL INT		INTER-		
NAME	NO.	FACET	1/0	DESCRIPTION
ALE (AS)	26	S	ı	Address-latch enable/address strobe. ALE( $\overline{AS}$ ) is an address-latch enable in the Intel mode and an address strobe in the Zilog mode. ALE ( $\overline{AS}$ ) is active high for an Intel subsystem and active low for a Zilog subsystem.
ARBCLKO	7	М	0	Arbitration clock output. ARBCLKO is equal to the input on ARBCLKI divided by the binary-coded divisor input on ARBPGM $(1-0)$ .
ARBCLKI	5	M	I	Arbitration clock input. ARBCLKI is the base clock used in arbitration for the attribute memory DRAM and the reset validation circuitry.
ARBPGM0 ARBPGM1	8 9	М	I	Arbitration clock divisor program. These two bits set the divisor for ARBCLKI. Divide by 1, 2, 4, and 8 are available.
BAUDOUT	38	U	0	Baud output. BAUDOUT is an active-low 16× signal for the transmitter section of the UART. The clock rate is established by the reference clock (UARTCLK) frequency divided by a divisor specified by the baud generator divisor latches. BAUDOUT may also be used for the receiver section by tying this output to the RCLK input.
CE1 CE2	94 62	Н	I	Card enable 1 and card enable 2 are active-low signals. $\overline{\text{CE1}}$ enables even-numbered address bytes, and $\overline{\text{CE2}}$ enables odd-numbered address bytes. A multiplexing scheme based on HA0, $\overline{\text{CE1}}$ , and $\overline{\text{CE2}}$ allows an 8-bit host to access all data on HD0 through HD7 if desired. These signals have internal pullup resistors.
CS	32	S	Τ	Chip select. CS is the active-low chip select from the Zilog or Intel microcontroller.
CTS	49	U	I	Clear to send. CTS is an active-low modem status signal whose condition can be checked by reading bit 4 (CTS) of the modem status register (MSR). Bit 0 (delta clear to send) of the MSR indicates that the signal has changed states since the last read from the MSR. If the modem-status interrupt is enabled when CTS changes states, an interrupt is generated.
DCD	48	U	I	Data carrier detect. $\overline{DCD}$ is an active-low modem-status signal whose condition can be checked by reading bit 7 (DCD) of the MSR. Bit 3 (delta data carrier detect) of the MSR indicates that the signal has changed states since the last read from the MSR. If the modem-status interrupt is enabled when $\overline{DCD}$ changes states, an interrupt is generated.
DSR	46	U	I	Data set ready. DSR is an active-low modem status signal whose condition can be checked by reading bit 5 (DSR) of the MSR. Bit 1 (delta data set ready) of the MSR indicates that the signal has changed states since the last read from the MSR. If the modem-status interrupt is enabled when DSR changes states, an interrupt is generated.
DTR	34	U	0	Data terminal ready. $\overline{\text{DSD}}$ is an active-low signal. When active, $\overline{\text{DTR}}$ informs the modem or data set that the UART is ready to establish communication. $\overline{\text{DTR}}$ is placed in the active state by setting the DTR bit 0 of the modem control register (MCR) to a high level. $\overline{\text{DTR}}$ is placed in the inactive state either as a result of a reset, doing a loop-mode operation, or resetting bit 0 (DTR) of the MCR.
EXTEND	1	U	I	FIFO extend. When EXTEND is high, the UART is configured as a standard TL16C550 with 16-byte transmit and receive FIFOs. When EXTEND is low and FIFO control register (FCR) bit 5 is high, the FIFOs are extended to 64 bytes and the receiver-interrupt trigger levels adjust accordingly. EXTEND low in conjunction with FIFO control register (FCR) bit 4 set high enables the auto-RTS function.
GND	4,6,13,16,30, 39,41,43,54, 66,68,69,80,91	M		Common ground

<sup>†</sup> Host = H, Subsystem = S, UART = U, Miscellaneous = M



### **Terminal Functions**

TERMINAL		INTER- FACET	1/0	DESCRIPTION	
NAME	NO.				
HA0 HA1 HA2 HA3 HA4 HA5 HA6	78 79 81 82 83 84	Н		The 10-bit address bus addresses the attribute memory (bits 1–8) and addresses the internal UART as either PCMCIA I/O (bits 0–2) or as a standard COM port (bits 0–9).	
HA7 HA8 HA9	87 90 92				
HD0 HD1 HD2 HD3 HD4 HD5 HD6 HD7	77 76 75 100 99 98 96 95	Н	I/O	The 8-bit bidirectional data bus transfers data to and from the attribute memory and the internal UART.	
INPACK	71	Н	0	Input port acknowledge. INPACK is an active-low output signal that is asserted when the card responds to an I/O read cycle at the address on the HA bus.	
IORD	63	Н	I	I/O read strobe. IORD is an active-low input signal activated to read data from the card I/O space. The REG signal and at least one of the card enable inputs (CE1, CE2) must also be active for the I/O transfer to take place. This signal has an internal pullup resistor.	
ĪOWR	64	Н	I	I/O <u>write</u> strobe. IORW is an active-low input signal activated to <u>write</u> data to the card I/O space. The REG signal and at least one of the card enable inputs (CE1, CE2) must also be active for the I/O transfer to take place. This signal has an internal pullup resistor.	
ĪREQ	88	Н	0	Interrupt request. IREQ is an active-low output signal asserted by the card to indicate to the CPU that a card device requires host software service. This signal doubles as READY/BU during power-up initialization.	
IRQ	27	S	0	Interrupt request. This active-high IRQ to the subsystem indicates a host CPU write to attribu memory has occurred.	
NANDOUT	12	М	0	This is a production test output.	
ŌĒ	93	Н	I	Output enable. OE is an active-low input signal used to gate memory read data from the card. This signal has an internal pullup resistor.	
OUT1 OUT2	37 44	U	0	Output 1 and output 2 are active-low signals. OUT1 and OUT2 are user-defined output terminals that are set to their active state by setting respective MCR bits (OUT1 and OUT2) high. OUT1 and OUT2 are set to their inactive (high) state as a result of a reset, doing loop-mode operation, or by resetting bit 2 (OUT1) or bit 3 (OUT2) of the MCR. This signal has an open-drain outputs.	
RCLK	40	U	ı	Receiver clock. RCLK is the 16x-baud-rate clock input for the receiver section of the UART.	
RD(DS)	29	S	I	Read enable or data strobe input. $\overline{\text{RD}}(\overline{\text{DS}})$ is the active-low read enable in the Intel mode and the active-low data strobe in the Zilog mode.	
REG	73	Н	I	Attribute memory select. This active-low input signal is generated by the host CPU and accesses attribute memory ( $\overline{OE}$ and $\overline{WE}$ active) and I/O space ( $\overline{IORD}$ or $\overline{IOWR}$ active). PCMCIA common memory access is excluded. This signal has an internal pullup resistor and hysteresis on the input buffer.	
RESET	67	Н	I	Reset. RESET is an active-high input that serves as the master reset for the device. RESET clears the UART, placing the card in an unconfigured state. This signal has an internal pullup resistor.	
RI	50	U	I	Ring indicator. $\overline{RI}$ is an active-low modem status signal whose condition can be checked by reading bit 6 (RI) of the MSR. The trailing-edge ring indicator (TERI) bit 2 of the MSR indicates that $\overline{RI}$ has transitioned from a low to a high state since the last read from the MSR. If the modem status interrupt is enabled when this transition occurs, an interrupt is generated.	

<sup>†</sup> Host = H, Subsystem = S, UART = U, Miscellaneous = M



### **Terminal Functions**

TERMINAL		INTER- FACE <sup>†</sup>	1/0	DESCRIPTION	
RST	11	М	0	This is the qualified active-low reset signal. RST has a fail-safe open-drain output.	
RTS	35	U	0	Request to send is an active-low signal. When active, $\overline{\text{RTS}}$ informs the modem of the data set that the UART is ready to receive data. $\overline{\text{RTS}}$ is set to its active state by setting the RTS modem control register bit and is set to its inactive (high) state either as a result of a reset, doing loop-mode operation, or by resetting bit 1 (RTS) of the MCR.	
SA0 SA1 SA2 SA3 SA4 SA5 SA6 SA7	53 55 56 57 58 59 61 65	S	ı	When SSAB is high, this is the subsystem address bus and SAD (7–0) is the subsystem data bus. When SSAB is low, this bus is not used and SAD(7–0) is the subsystem multiplexed address/data bus.	
SA8	24	S	Т	Address bit 8 is bit 8 of the subsystem address bus.	
SAD0 SAD1 SAD2 SAD3 SAD4 SAD5 SAD6 SAD7	25 23 20 19 18 17 15	S	I/O	Subsystem address/data 7–0. This is a multiplexed bidirectional address/data bus to the attribute-memory DPRAM and CCRs when SSAB is low. This becomes a bidirectional data bus when SSAB is high.	
SELZ/Ī	28	S	ı	Select Zilog or Intel mode. $SELZ/\bar{I}$ is used to select between a Zilog-like or Intel-like microcontroller. 1 = Zilog, 0 = Intel.	
SIN	33	U	ı	Serial data input. SIN moves information from the communication line or modem TL16PC564B UART receiver circuits. Data on the serial bus is disabled when operatin loop mode.	
SOUT	45	U	0	Serial out. SOUT is the composite serial data output to a connected communication de SOUT is set to the marking (logic 1) state as a result of a reset.	
SSAB	3	S	ı	Separate subsystem address bus. SSAB is used to select between a multiplexed addre bus subsystem interface (SSAB = 0) and a subsystem interface with separate address a buses (SSAB = 1). This signal has an internal pulldown resistor.	
STSCHG	74	Н	0	Status change. STSCHG is an optional active-low output signal used to alert the host that a subsystem write to attribute memory has occurred. This signal has an open-drain output.	
TESTOUT	70	М	0	This is a production test output.	
UARTCLK	51	М	0	UART clock. UARTCLK is a clock output whose frequency is determined by the frequency on XIN and the divisor value on the PGMCLK register.	
VCC	10,21,22,36, 47,52,60, 72,86,97	М		3.3-V or 5-V supply voltage	
VTEST	2	М	I	VTEST is an active-high production test input with an internal pulldown resistor. It can be left open or tied to ground.	
WE	89	Н	I	Write enable. WE is an active-low input signal used for strobing attribute-memory write data into the card. This signal has an internal pullup resistor	
WR(R/W)	31	S	I	Write or read/write enable. $\overline{WR}(R/\overline{W})$ is the active-low write enable in the Intel mode and read/write in the Zilog mode.	
XIN	42	М	Ī	Crystal input. XIN is a clock input divided internally based on the PGMCLK register value, then used as the primary UART clock input.	

 $<sup>^{\</sup>dagger}$  Host = H, Subsystem = S, UART = U, Miscellaneous = M



### detailed description

### reset-validation circuit

A reset-validation circuit has been implemented to qualify the active-high RESET input. At power up, the level on the  $\overline{RST}$  output is unknown. Whenever RESET is stable for at least eight ARBCLKIs,  $\overline{RST}$  reflects the inverted state of that stable value of RESET. Any changes on RESET must be valid for eight ARBCLKI clocks before the change is reflected on  $\overline{RST}$ . This 8-clock filter provides needed hysteresis on the master reset input.  $\overline{RST}$  is driven by a low-noise, open-drain, fail-safe output buffer.

### host CPU memory map

The host CPU attribute memory space is mapped as follows:

Address Mode (hex)

3EE

3EF

Host CPU Address Bits 9–1 (HA0 = 0)	Attribute Memory Space
0 - 255	CIS
256	CCR0
257	CCR1
258	CCR2
259	CCR3
260	CCR4
261	CCR5
262	CCR6
263	CCR7

The host CPU I/O space is mapped as follows:

	•	1441.000	11000 (110	~)	
<b>Normal Mode</b>	COM1	COM <sub>2</sub>	COM3	COM4	I/O Space
$0 (DLAB = 0)^{\dagger}$	3F8	2F8	3E8	2E8	UART receiver buffer register (RBR) – read only
$0 (DLAB = 0)^{\dagger}$	3F8	2F8	3E8	2E8	UART transmitter holding register (THR) – write only
$0 (DLAB = 1)^{\dagger}$	3F8	2F8	3E8	2E8	UART divisor latch LSB (DLL)
1 (DLAB = $0$ ) <sup>†</sup>	3F9	2F9	3E9	2E9	UART interrupt enable register (IER)
1 (DLAB = 1) $^{\dagger}$	3F9	2F9	3E9	2E9	UART divisor latch MSB (DLM)
2	3FA	2FA	3EA	2EA	UART interrupt identification register (IIR) – read only
2	3FA	2FA	3EA	2EA	UART FIFO control register (FCR) – write only
3	3FB	2FB	3EB	2EB	UART line control register (LCR)
4	3FC	2FC	3EC	2EC	UART modem control register (MCR) – bit 5 read only
5	3FD	2FD	3ED	2ED	UART line status register (LSR)

2EE

2EF

UART modem status rgister (MSR)

UART scratch register (SCR)

3FE

3FF

### subsystem memory map

6

The subsystem attribute memory space is mapped as follows:

2FE

2FF

Subsystem Address Bits 8-0	Attribute Memory Space
0 – 255	CIS
256	CCR0
257	CCR1
258	CCR2
259	CCR3
260	CCR4
261	CCR5
262	CCR6
263	CCR7



<sup>&</sup>lt;sup>†</sup> DLAB is bit 7 of the line control register (LCR).

SLLS225A - MARCH 1996 - REVISED FEBRUARY 1998

### subsystem memory map (continued)

The subsystem control space is mapped as follows:

Subsystem Address Bits 8-0	Control Space
272	Control Register
288	PGMCLK Register (write only)

The subsystem UART space is mapped as follows:

Subsystem Address Bits 8-0	UART Space
304	UART MCR bit 5 (write only)
304	UART DLL (read only)
305	UART IER (read only)
306	UART FCR (read only)
307	UART LCR (read only)
308	UART MCR (read only)
309	UART LSR (read only)
310	UART MSR (read only)
311	UART DLM (read only)
320	UART transmitter FIFO (read only)†
320	UART receiver FIFO (write only)†

<sup>†</sup>Only when serial bypass mode is enabled

### host CPU/attribute-memory interface

The host CPU/attribute-memory interface is comprised of one port of the internal DPRAM, the eight CCRs, and necessary control circuitry. Signals HA0 and CE1 are gated together internally so that the output of the gate is low when both signals have been asserted by the host CPU. This output is combined with REG and the decoded address, HA(9–1), to provide the chip enable for the DPRAM and CCRs. This composite chip enable in combination with WE or OE allows writes and reads to the DPRAM and CCRs.

### subsystem/attribute-memory interface

The subsystem/attribute-memory interface is comprised of the second port of the internal DPRAM, the eight CCRs, and necessary control circuitry. When in multiplexed mode (SSAB = 0), the combination of signals SELZ/ $\bar{l}$  and ALE( $\bar{AS}$ ) allows either a positive-pulse Intel or a negative-pulse Zilog address latch-enable strobe to latch the address on SA8 and SAD(7-0). When in the Zilog mode (SELZ/ $\bar{l}$  high), the combination of read/write [ $\bar{WR}(R/\bar{W})$ ], data strobe [ $\bar{RD}(\bar{DS})$ ], and decoded address allows ZBUS access. When in the Intel configuration (SELZ/ $\bar{l}$  low), the combination of read [ $\bar{RD}(\bar{DS})$ ], write [ $\bar{WR}(R/\bar{W})$ ], and decoded address allows IBUS access.

When in nonmultiplexed mode (SSAB = 1), SA(7-0) become the lower-order address bits, SAD(7-0) are strictly the bidirectional data bus, and  $ALE(\overline{AS})$  is nonfunctional. All other interface signals function the same.

SSAB	SELZ/Ī	RD(DS)	$\overline{WR}(R/\overline{W})$	Address	Operation
0	0	0	1	SA8, SAD(7-0)	Intel read
0	0	1	0	SA8, SAD(7-0)	Intel write
0	1	0	1	SA8, SAD(7-0)	Zilog read
0	1	0	0	SA8, SAD(7-0)	Zilog write
1	0	0	1	SA(8-0)	Intel read
1	0	1	0	SA(8-0)	Intel write
1	1	0	1	SA(8-0)	Zilog read
1	1	0	0	SA(8-0)	Zilog write



SLLS225A - MARCH 1996 - REVISED FEBRUARY 1998

#### attribute-memory arbitration

Arbitration for the attribute memory is necessary whenever there is simultaneous access to the same DPRAM or CCR address for the conditions of:

- Host CPU read and subsystem write
- Host CPU write and subsystem read
- Host CPU write and subsystem write

If arbitration were not provided, attribute-memory data would be corrupted and invalid data read due to uncontrolled access to the same DPRAM or CCR address.

The arbitration control circuitry synchronizes the asynchronous accesses of the host CPU and subsystem to the DPRAM and CCR and controls the access based on the pending host CPU and subsystem attribute-memory operation. The synchronizing and control circuitry needs a clock called the arbitration clock. The external clock (ARBCLKI) goes through a programmable divider and can be divided by one, two, four, or eight to generate a clock frequency within an allowed range for the arbitration logic to work correctly. The output of this frequency divider is named ARBCLKO. The programmable divider bits are defined as follows:

ARBPGM1	ARBPGM0	INTERNAL ARITRATION CLOCK
L	L	ARBCLKI/1
L	Н	ARBCLKI/2
Н	L	ARBCLKI/4
Н	Н	ARBCLKI/8

The upper period limit of ARBCLKO is N/6, where N (ns) is the shortest of the two attribute-memory accesses, host CPU or subsystem. The lower period limit of ARBCLKO is based on the DPRAM specifications at the supply voltage used:

5 V = 14-ns clock cycle (71 MHz)

3 V = 26-ns clock cycle (38.5 MHz)

For any arbitration condition, attribute-memory access is controlled to ensure valid data is read for a port that is doing a read operation and valid data is written for a port that is doing a write operation. When both the host CPU and subsystem are performing simultaneous write operations to the same address, the host CPU is allowed to write and the subsystem write is ignored.

### host CPU/subsystem handshake

Two signals are provided for handshaking between the host CPU and the subsystem. The active-high IRQ signifies to the subsystem that the host CPU has written data into attribute memory. The subsystem can clear IRQ by writing a 1 to bit 6 of the subsystem control register. The active-low STSCHG signifies to the host CPU that the subsystem has written data to attribute memory provided bit 2 of the subsystem control register (STSCHG enable) is high. The host CPU can clear STSCHG by reading any location in attribute memory. The control of these signals is synchronized to ARBCLKO to ensure there are no false assertions/deassertions.

There is additional arbitration performed for instances of simultaneous assertion/deasseration of IRQ or STSCHG. When a subsystem write and host CPU read occurs simultaneously, STSCHG may be briefly deasserted prior to being asserted, but the write ultimately wins arbitration. When the host CPU read occurs more than one-half an arbitration clock after the subsystem write, STSCHG is deasserted. IRQ is arbitrated in a similar fashion.

SLLS225A - MARCH 1996 - REVISED FEBRUARY 1998

#### host CPU/UART interface

The UART select is derived from either host CPU address information or logic levels on  $\overline{\text{CE1}}$ ,  $\overline{\text{CE2}}$  and  $\overline{\text{REG}}$ . In the address mode, host CPU address bits HA9, HA7, HA6, HA5, and HA3 are combined with conditional derivatives of HA4 and HA8 to select the UART (HA4 and HA8 select COM ports 1–4 based on settings in the subsystem control register).  $\overline{\text{CE1}}$  and  $\overline{\text{CE2}}$  are combined such that either of these two signals in combination with  $\overline{\text{REG}}$  enable the UART in the event that these signals are present. In the event that  $\overline{\text{CE1}}$  or  $\overline{\text{CE2}}$  are not present, the UART must be accessed in the address mode previously described. The UART select in conjunction with  $\overline{\text{IORD}}$  and  $\overline{\text{IOWR}}$  allows host CPU accesses to the UART. Host CPU address bits HA2–HA0 are decoded to select which UART register is to be accessed.

All UART registers remain intact with the exception of the FIFO control register (FCR) and the modem-control register (MCR). The FCR (host CPU write-only address 2) bits 4 and 5 in conjunction with EXTEND control RTS operation and FIFO depth as follows:

BIT 5	BIT 4	EXTEND	RTS OPERATION	FIFO DEPTH
Х	Х	Н	Normal	16 bytes
0	0	L	Normal	16 bytes
0	1	L	Auto	16 bytes
1	0	L	Normal	64 bytes
1	1	Ĺ	Auto	64 bytes

FCR bit 5 high and EXTEND low redefine the receiver FIFO trigger levels set by FCR bits 6 and 7 as follows:

BIT 7	BIT 6	TRIGGER LEVEL
0	0	1
0	1	16
1	0	32
1	1	56

The MCR (host CPU address 4) bit 5 is read only. Bit 5 is controlled by the subsystem to enable (high) the auto-CTS mode of operation

### subsystem/UART interface

The <u>UART</u> provides a serial-communications channel to the subsystem with enhanced <del>RTS</del> control (see auto-<del>RTS</del> description). This channel is capable of operating at 115 kbps and is the main communications channel to the subsystem (refer to the TL16C550 specification for the detailed description of the serial-communications channel).

Many of the UART registers have been mapped into the subsystems memory space as read only. In addition, MCR bit 5 (subsystem address 130 hex) is controlled by the subsystem to enable (high) auto-CTS. The subsystem can read the MCR at address 134 hex. When reading the FCR (subsystem address 132 hex), bits 1 and 2 are always high, and bits 4 and 5 are low only when EXTEND is low and the host CPU has set them high (64-byte FIFOs and auto-RTS enabled) (refer to the subsystem memory map).

### subsystem control register

The subsystem control register is an 8-bit register located at subsystem address 110 (hex). This register is programmed based on host CPU configuration information and has a default selection of COM2 after a valid reset. The bit definitions are as follows (0 = LSB):

Bits 0 and 1 define which host COM port the UART is connected to when the chip is in the address mode. COM2 is the default (power-up) condition.

BIT 1	BIT 0	COM PORT
0	0	COM1
1	0	COM2
0	1	COM3
1	1	COM4

Bit 2 is a host CPU interrupt-enable bit. When bit 2 is set, any subsystem attribute-memory write cycle causes STSCHG to be asserted. Bit 2 is cleared after a valid reset.

Bit 3 enables or disables address-mode selection as described in the host CPU/UART interface description. Bit 3 is cleared (disabling the address mode) after a valid reset.

Bits 4 and 5 together ensure adherence to PCMCIA power-up requirements. At power up, the card must operate as a memory card and all host CPU I/O operations must be disabled. IREQ, which doubles as the host CPU READY/BUSY line, powers up low, indicating that the memory card is busy. Once the subsystem initializes attribute memory, the subsystem sets bit 4 to indicate that the memory card is ready. Then bit 5 is reset, changing the configuration from a memory card to an I/O card, enabling host CPU UART accesses. IREQ now becomes the host CPU interrupt-request line.

BIT 5	BIT 4	CONFIGURATION
1	0	Memory card, I/O operation (UART) disabled; IREQ is low, indicating card is busy (power-up and reset condition)
1	1	Memory card, I/O operation (UART) disabled; IREQ is high, indicating card is ready
0	Х	I/O card, I/O operation (UART) enabled; IREQ now functions as the host CPU interrupt-request line

Bit 6 is a self-clearing bit that resets the subsystem IRQ signal. Writing a 1 to this location clears the IRQ interrupt.

Bit 7 enables or disables serial-bypass mode as described in the subsystem serial-bypass-mode description. Bit 7 is cleared (disabling serial-bypass mode) after a valid reset.

### subsystem PGMCLK register/divide-by-n circuit

The subsystem PGMCLK register is a 6-bit write-only register located at address 120 hex and is used to select the divisor of the divide-by-n-and-a-half circuitry. Any write to this register generates a reset to the UART and the divide-by-n circuitry.

The divide-by-n circuitry allows for a divisor from 0 to 31.5 in 0.5 increments (PGMCLK0 is the half bit). The divided clock output drives the UART clock input and can be seen on UARTCLK. The UART requires a clock with a minimum high pulse duration of 50 ns and a minimum low pulse duration of 50 ns (10-MHz maximum operating frequency). A programmed divisor between 2 and 7.5 drives the UART clock low for one XIN clock cycle for integer divisors and one-and-a-half XIN clock cycles for integer-plus-a-half divisors. A programmed divisor of eight or greater drives the UART clock low for four XIN clock cycles for integer divisors. A

SLLS225A - MARCH 1996 - REVISED FEBRUARY 1998

four-and-a-half XIN clock cycles for integer-plus-a-half divisors. Based on the above parameters, the acceptable XIN/divisor combinations can be derived. The precision of the programmable clock generator for integer-plus-a-half divisors depends on the closeness to a 50% duty cycle for the XIN input clock.

#### NOTE

With a divisor less than or equal to 8 (whole number), the UART clock will have a low pulse equal to one clock cycle of the XIN clock. Caution should be used as noted in the following example.

A 20 MHz clock period yields 50 ns total, including rise time and fall time, if a divisor of less than or equal to 8 (whole number) is used. This provides a total down period less than 50 ns to the UART clock, which is less than that which is required for the UART to function properly.

Caution should be used when selecting the XIN and divisor combination.

PGMCL	K(0-5) VALUE (HEX)	RESULT
0	(0)	No clock (driven high)
0.5	(1)	Divide-by-1
1	(2)	Divide-by-1
1.5	(3)	Divide-by-1
2	(4) to 31.5 (3F)	Divide-by-2 to divide-by-31.5

### subsystem serial-bypass mode

The optional serial-bypass mode is implemented to allow a high-throughput path to/from the host CPU. When this mode is enabled and subsystem control register bit 7 is high, the serial portion of the UART is bypassed and the subsystem has direct parallel access to the receiver FIFO (write address 140 hex) and the transmitter FIFO (read address 140 hex). All host CPU interrupts operate normally except for receiver parity, framing, and breaking interrupts.

### auto-CTS operation

The optional auto-CTS operation is implemented so that the host CPU cannot overflow the modem receive buffer. Auto-CTS operation is enabled when the subsystem sets MCR (subsystem address 130 hex) bit 5 high. When enabled, deactivating CTS (high) halts the transmitter section of the UART after it completes the current transfer. Once CTS is reactivated (low) by the modem, transfers resume. Interrupt operation is not affected by enabling auto-CTS.

### auto-RTS operation

The optional auto-RTS operation is implemented so that the subsystem cannot overflow the receiver FIFO. Auto-RTS operation is enabled when FCR bit 4 is high and EXTEND is low and operates independently from the trigger-level circuitry. In the 16-byte FIFO mode, the RTS bit in the modem-control register (bit 1) clears when 14 characters are in the receive FIFO. This action causes RTS to go high (inactive). In the 64-byte FIFO mode, the MCR RTS bit clears when 56 characters are in the receiver FIFO. Interrupt operation is not affected and operates the same way in either auto-RTS or nonauto-RTS mode. When enabled, a receive-data-available interrupt occurs after the trigger level is reached. The MCR RTS bit must then be set by the host CPU after the receiver FIFO has been read.



### power consumption

The TL16PC564A has low power consumption under the following conditions:

- 32-MHz signal on XIN
- Divide-by-n is set to give a 1.8432-MHz UARTCLK signal
- Nominal data
- V<sub>CC</sub> = 5 V

The current (I<sub>CC</sub>) and power consumption are 18 mA (typical) and 90 mW (typical), respectively. These current and power figures fluctuate with changes in the above conditions.

### absolute maximum ratings over operating free-air temperature range†

Supply voltage range, V <sub>CC</sub>	0.5 V to 6 V
Input voltage range, V <sub>I</sub> (standard)	$-0.5 \text{ V to V}_{CC} + 0.5 \text{ V}$
Input voltage range, V <sub>I</sub> (fail safe)	
Output voltage range, V <sub>O</sub> (standard)	$-0.5 \text{ V to V}_{CC} + 0.5 \text{ V}$
Output voltage range, V <sub>O</sub> (fail safe)	0.5 V to 6.5 V
Input clamp current, $I_{IK}$ ( $V_I < 0$ or $V_I > V_{CC}$ ) (see Note 1)	±20 mA
Output clamp current, $I_{OK}$ ( $V_O < 0$ or $V_O > V_{CC}$ ) (see Note 2)	±20 mA
Operating free-air operating temperature range, T <sub>A</sub>	0°C to 70°C
Storage temperature range, T <sub>stg</sub>	–65°C to 150°C

<sup>†</sup> Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. Applies for external input and bidirectional buffers.  $V_I > V_{CC}$  does not apply to fail-safe pins.

### recommended operating conditions

### low voltage (3.3 V nominal)

		MIN	NOM	MAX	UNIT
Supply voltage V	TL16PC564B	3	3.3	3.6	V
Supply voltage, V <sub>CC</sub>	TL16PC564BLV	2.7	3	3.3	V
Input voltage, V <sub>I</sub>		0		Vсс	V
High-level input voltage (CMOS), V	IH (see Note 3)	0.7V <sub>CC</sub>			V
Low-level input voltage (CMOS), V	L (see Note 3)			0.3VCC	V
Output voltage, VO (see Note 4)		0		Vcc	V
High-level output current, IOH	All outputs except RST, STSCHG, OUT1, OUT2 (see Note 5)			1.8	mA
Low-level output current, IOI	All outputs except RST			3.2	mA
Low-level output current, IOL	RST			6.4	IIIA
Input transition time, t <sub>t</sub>		0		25	ns
Operating free-air temperature rang	ge, T <sub>A</sub>	0	25	70	°C
Junction temperature range, T <sub>J</sub> (se	e Note 6)	0	25	115	°C

NOTES: 3. Meets TTL levels, VIHmin = 2 V and VILmax = 0.8 V on nonhysteresis inputs

- 4. Applies for external output buffers
- 5. RST, STSCHG, OUT1, and OUT2 are open-drain outputs, so I<sub>OH</sub> does not apply.
- 6. These junction temperatures reflect simulation conditions. Absolute maximum junction temperature is 150°C. The customer is responsible for verifying junction temperature.



<sup>2.</sup> Applies for external output and bidirectional buffers. VO > VCC does not apply to fail-safe pins.

SLLS225A - MARCH 1996 - REVISED FEBRUARY 1998

### standard voltage (5 V nominal)

		MIN	NOM	MAX	UNIT
Supply voltage, V <sub>CC</sub>		4.75	5	5.25	V
Input voltage, V <sub>I</sub>		0		Vcc	V
High-level input voltage (CMOS),	VIH	0.7V <sub>CC</sub>			V
Low-level input voltage (CMOS),	√IL			0.2V <sub>CC</sub>	V
Output voltage, VO (see Note 4)		0		Vcc	V
High-level output current, IOH	All outputs except RST, STSCHG, OUT1, OUT2 (see Note 5)			4	mA
Low lovel output ourrent le	All outputs except RST			4	mA
Low-level output current, IOL	RST			8	IIIA
Input transition time, t <sub>t</sub>		0		25	ns
Operating free-air temperature ra	nge, T <sub>A</sub>	0	25	70	°C
Junction temperature range, T <sub>J</sub> (s	see Note 6)	0	25	115	°C

NOTES: 4. Applies for external output buffers

- 5. RST, STSCHG, OUT1, and OUT2 are open-drain outputs, so I<sub>OH</sub> does not apply.
- 6. These junction temperatures reflect simulation conditions. Absolute maximum junction temperature is 150°C. The customer is responsible for verifying junction temperature.

## electrical characteristics over recommended ranges of operating free-air temperature and supply voltage (unless otherwise noted)

### low voltage (3.3 V nominal)

	PARAMETER	TEST CONDITIONS	MIN	MAX	UNIT
VOH	High-level output voltage	I <sub>OH</sub> = rated	V <sub>CC</sub> -0.55		V
VOL	Low-level output voltage	I <sub>OL</sub> = rated		0.5	V
V <sub>IT+</sub>	Positive-going input threshold voltage (see Note 7)			0.7 V <sub>CC</sub>	V
V <sub>IT</sub> _	Negative-going input threshold voltage (see Note 7)		0.3 V <sub>CC</sub>		V
V <sub>hys</sub>	Hysteresis (V <sub>IT+</sub> - V <sub>IT-</sub> ) (see Note 7)		0.1 V <sub>CC</sub>	0.3 V <sub>CC</sub>	V
loz	3-state-output high-impedance current (see Note 8)	$V_I = V_{CC}$ or GND		±10	μΑ
Ι <sub>Ι</sub> L	Low-level input current (see Note 9)	V <sub>I</sub> = GND		-1	μΑ
lн	High-level input current (see Note 10)	VI = VCC		1	μΑ

### standard voltage (5 V nominal)

	PARAMETER	TEST CONDITIONS	MIN	MAX	UNIT
Vон	High-level output voltage	I <sub>OH</sub> = rated	V <sub>CC</sub> -0.8		V
VOL	Low-level output voltage	I <sub>OL</sub> = rated		0.5	V
V <sub>IT+</sub>	Positive-going input threshold voltage (see Note 7)			0.7 V <sub>CC</sub>	V
$V_{IT-}$	Negative-going input threshold voltage (see Note 7)		0.2 V <sub>CC</sub>		V
V <sub>hys</sub>	Hysteresis (V <sub>IT+</sub> - V <sub>IT-</sub> ) (see Note 7)		0.1 V <sub>CC</sub>	0.3 V <sub>CC</sub>	V
loz	3-state-output high-impedance current (see Note 8)	$V_I = V_{CC}$ or GND		±10	μΑ
I <sub>I</sub> L	Low-level input current (see Note 9)	V <sub>I</sub> = GND		-1	μΑ
lіН	High-level input current (see Note 10)	VI = VCC		1	μΑ

NOTES: 7. Applies for external input and bidirectional buffers with hysteresis

- 8. The 3-state or open-drain output must be in the high-impedance state.
- 9. Specifications only apply with pullup terminator turned off.
- 10. Specifications only apply with pulldown terminator turned off.



SLLS225A - MARCH 1996 - REVISED FEBRUARY 1998

### XIN timing requirements over recommended operating free-air temperature range (see Figure 1)

		TEST C	ONDITIONS	MIN	MAX	UNIT
	Input fraguency	$V_{CC} = 3.3 \text{ V},$	See Note 11		50	MHz
	Input frequency	$V_{CC} = 5 V$			60	IVITIZ
	Cycle time, XIN	$V_{CC} = 3.3 \text{ V},$	See Note 11	20		ns
t <sub>c1</sub>	Cycle time, Am	$V_{CC} = 5 V$		16.7		110
	Pulse duration, XIN clock high	$V_{CC} = 3.3 \text{ V},$	See Note 11	10		no
t <sub>w1</sub>	Pulse duration, Ain clock nigh	V <sub>CC</sub> = 5 V		8		ns
	Pulse duration, VIN clock law	V <sub>CC</sub> = 3.3 V,	See Note 11	10		no
t <sub>w2</sub>	Pulse duration, XIN clock low	V <sub>CC</sub> = 5 V	•	8		ns

NOTE 11: TL16PC564BLV device tested at  $V_{CC} = 3 \text{ V}$ .

## clock switching characteristics over recommended operating free-air temperature range (see Figure 1)

	PARAMETER	TEST C	ONDITIONS	MIN	MAX	UNIT
	Delay time. VINT to LIARTOLKT	$V_{CC} = 3.3 \text{ V},$	See Note 11		14	ns
<sup>t</sup> d1	Delay time, XIN↑ to UARTCLK↑	V <sub>CC</sub> = 5 V			8	115
t 10	Delay time, XIN↓ to UARTCLK↓	$V_{CC} = 3.3 \text{ V},$	See Note 11		16	ns
t <sub>d2</sub>	Delay time, AIN & to OAKTOLK	V <sub>CC</sub> = 5 V			10	115
	Delay time, XIN↑ to UARTCLK↓	$V_{CC} = 3.3 \text{ V},$	See Note 11		19.8	20
t <sub>d3</sub>	Delay time, AIN TO DANTOLK	V <sub>CC</sub> = 5 V			13	ns
	Delay time, XIN↑ to UARTCLK↑	$V_{CC} = 3.3 \text{ V},$	See Note 11		20.6	20
<sup>t</sup> d4	Delay time, AINT to OAKTOLKT	V <sub>CC</sub> = 5 V			13.5	ns
+	Delay time, XIN↓ to UARTCLK↑	V <sub>CC</sub> = 3.3 V,	See Note 11		21	ne
t <sub>d5</sub>	Delay little, Ally to OAKTOLKT	V <sub>CC</sub> = 5 V			13.8	ns

NOTE 11: TL16PC564BLV device tested at  $V_{CC} = 3 \text{ V}$ .

## host CPU I/O read-cycle timing requirements over recommended ranges of operating free-air temperature and supply voltage (see Figure 2 and Note 12)

		MIN	MAX	UNIT
t <sub>h1</sub>	Hold time, HA(9−0) valid after IORD↑	20		ns
t <sub>h2</sub>	Hold time, REG↑ valid after IORD↑	0		ns
t <sub>w4</sub>	Pulse duration, IORD low	165		ns
t <sub>su1</sub>	Setup time, HA(9−0) valid before IORD↓	70		ns
t <sub>su2</sub>	Setup time, CEx↓ before IORD↓	5		ns
t <sub>h3</sub>	Hold time, CEx↑ after IORD↑	20		ns
t <sub>h4</sub>	Hold time, HD(7−0) valid after IORD↑	0		ns
t <sub>su3</sub>	Setup time, REG↓ before IORD↓	5		ns
<sup>t</sup> d6	Delay time, HD(7−0) valid after IORD↓		100	ns

NOTE 12: The maximum load on INPACK is one low power shot with 50-pF total load. All timing is measured in nanoseconds.

## host CPU I/O read-cycle switching characteristics over recommended ranges of operating free-air temperature and supply voltage (see Figure 2 and Note 11)

	PARAMETER  7 Delay time, INPACK↓ after IORD↓		MAX	UNIT
t <sub>d7</sub>	Delay time, INPACK↓ after IORD↓		45	ns
t <sub>d8</sub>	Delay time, INPACK↑ after IORD↑		45	ns

NOTE 12: The maximum load on INPACK is one low power Schottky (LSTTL) diode with 50-pF total load. All timing is measured in nanoseconds.



SLLS225A - MARCH 1996 - REVISED FEBRUARY 1998

## host CPU I/O write-cycle timing requirements over recommended ranges of operating free-air temperature and supply voltage (see Figure 3)

		MIN	MAX	UNIT
t <sub>su4</sub>	Setup time, HD(7−0) valid before IOWR↓	60		ns
t <sub>h5</sub>	Hold time, HA(9−0) valid after IOWR↑	20		ns
t <sub>w6</sub>	Pulse duration, IOWR low	165		ns
t <sub>su5</sub>	Setup time, HA(9−0) valid before IOWR↓	70		ns
th6	Hold time, REG↑ after IOWR↑	0		ns
t <sub>su6</sub>	Setup time, CEx↓ before IOWR↓	5		ns
t <sub>h7</sub>	Hold time, CEx↑ after IOWR↑	20		ns
t <sub>su7</sub>	Setup time, REG↓ before IOWR↓	5		ns
t <sub>h8</sub>	Hold time, HD(7−0) valid after IOWR↑	30		ns

## transmitter switching characteristics over recommended ranges of operating free-air temperature and supply voltage (see Figure 4)

	PARAMETER	TEST CONDITIONS	MIN	MAX	UNIT
t <sub>d9</sub>	Delay time, SOUT↓ after IOWR↑		8	24	Baud cycles
<sup>t</sup> d10	Delay time, IREQ↓ after SOUT↓		8	8	Baud cycles
<sup>t</sup> d11	Delay time, IREQ↓ after IOWR↑		16	32	Baud cycles
t <sub>d12</sub>	Delay time, IREQ↑ after IOWR↑	C <sub>L</sub> = 100 pF		140	ns
t <sub>d13</sub>	Delay time, IREQ↑ after IORD↑	C <sub>L</sub> = 100 pF		140	ns

### receiver switching characteristics over recommended ranges of operating free-air temperature and supply voltage (see Figure 5)

	PARAMETER	TEST CONDITIONS	MIN	MAX	UNIT
t <sub>d14</sub>	Delay time, sample CLK↑ after RCLK↑			100	ns
t <sub>d15</sub>	Delay time, IREQ↓ after SIN↓			1	RCLK cycles
td16	Delay time, IREQ↑ after IORD↑	C <sub>L</sub> = 100 pF		150	ns

## modem-control switching characteristics over recommended ranges of operating free-air temperature and supply voltage, $C_L = 100 \text{ pF}$ (see Figure 6)

	PARAMETER	MIN	MAX	UNIT
t <sub>d17</sub>	Delay time, RTS, DTR, OUT1, OUT2 ↓ or ↑ after IOWR↑		50	ns
<sup>t</sup> d18	Delay time, IREQ↓ after CTS, DSR, DCD↓		30	ns
t <sub>d19</sub>	Delay time, IREQ↑ after IORD↑		35	ns
t <sub>d20</sub>	Delay time, IREQ↓ after RI↑		30	ns



SLLS225A - MARCH 1996 - REVISED FEBRUARY 1998

## host CPU attribute-memory write-cycle timing requirements over recommended ranges of operating free-air temperature and supply voltage (see Figures 7 and 8)

		MIN	MAX	UNIT
t <sub>c2</sub>	Write cycle tlme, HA(9-0)	250		ns
t <sub>w8</sub>	Pulse duration, WE low	150		ns
t <sub>su8</sub>	Setup time, CEx↓ before WE↑	180		ns
t <sub>su9</sub>	Setup time, HA(9−0) before WE↑ (see Note 12)	180		ns
t <sub>su10</sub>	Setup time, HA(9−0) before WE↓ and CEx↓(see Note 13)	30		ns
tsu11	Setup time, <del>OE</del> ↑ before <del>WE</del> ↓	10		ns
t <sub>h</sub> 9	Hold time, HD(7−0) after WE↑	30		ns
t <sub>rec1</sub>	Recovery time, HA(9−0) after WE↑	30		ns
t <sub>su12</sub>	Setup time, HD(7−0) before WE↑	80		ns
t <sub>h10</sub>	Hold time, <del>OE</del> ↓ after <del>WE</del> ↑	10		ns
t <sub>su13</sub>	Setup time, CEx↓ before WE↓	0	·	ns
t <sub>h11</sub>	Hold time, CEx↑ after WE↑	20	·	ns

NOTE 13: The REG signal timing is identical to address signal timing.

## host CPU attribute-memory write-cycle switching characteristics over recommended ranges of operating free-air temperature and supply voltage (see Figure 7)

	PARAMETER			UNIT
tdis1	Disable time, HD(7–0) after $\overline{\text{WE}}\downarrow$		100	ns
t <sub>dis2</sub>	Disable time, HD(7−0) after OE↑		100	ns
t <sub>en1</sub>	Enable time, HD(7−0) after WE↑	5		ns
t <sub>en2</sub>	Enable time, HD(7−0) after $\overline{\text{OE}} \downarrow$	5		ns

## host CPU attribute-memory read-cycle timing requirements over recommended ranges of operating free-air temperature and supply voltage (see Figure 9)

		MIN	MAX	UNIT
t <sub>c3</sub>	Read cycle time	300		ns
t <sub>d22</sub>	Delay time, HD(7-0) after HA(9-0)		300	ns
t <sub>d23</sub>	Delay time, HD(7−0) after CEx↓		300	ns
t <sub>d24</sub>	Delay time, HD(7−0) after $\overline{\text{OE}}$ ↓		150	ns
th12	Hold time, HD(7-0) after HA(9-0)	0		ns
tsu14	Setup time, CEx↓ before OE↓	0		ns
th13	Hold time, HA(9−0) after OE↑	20		ns
t <sub>su15</sub>	Setup time, HA(9−0) before $\overline{\text{OE}} \downarrow$	30		ns
t <sub>h14</sub>	Hold time, <del>CE</del> x↑ after <del>OE</del> ↑	20		ns

## host CPU attribute-memory read-cycle switching characteristics over recommended ranges of operating free-air temperature and supply voltage (see Figure 9)

	PARAMETER			UNIT
t <sub>dis3</sub>	Disable time, HD(7−0) after CEx↑		100	ns
t <sub>dis4</sub>	Disable time, HD(7−0) after OE↑		100	ns
t <sub>en3</sub>	Enable time, HD(7−0) after CEx↓	5		ns
t <sub>en4</sub>	Enable time, HD(7−0) after OE↓	5		ns



SLLS225A - MARCH 1996 - REVISED FEBRUARY 1998

### subsystem Intel-mode timing requirements (32 MHz) (see Figure 10)

INTEL SYMBOL	JEDEC SYMBOL		MIN	MAX	UNIT
tLHLL	tw11	Pulse duration, ALE high	48		ns
t <sub>AVLL</sub>	tsu16	Setup time, SA8, SAD(7-0) valid to ALE low	21		ns
tPLLL	t <sub>d25</sub>	Delay time, CS low to ALE low	21		ns
tLLAX	th15	Hold time, SA8, SAD(7−0) valid after ALE↓	21		ns
tLLWL	t <sub>d26</sub>	Delay time, ALE low to WR low	16		ns
tLLRL	t <sub>d27</sub>	Delay time, ALE low to RD low	16		ns
tWHLH	t <sub>d28</sub>	Delay time, WR high to ALE high	21		ns
<sup>t</sup> AFRL	t <sub>d29</sub>	Delay time, SA8, SAD(7-0) in high-impedance state to RD low	0		ns
<sup>t</sup> RLRH	tw12	Pulse duration, RD low	120		ns
tWLWH	tw13	Pulse duration, WR low	120		ns
<sup>t</sup> RHAX	t <sub>d30</sub>	Delay time, RD high to SA8, SAD(7-0) active	48		ns
tWHDX	<sup>t</sup> h16	Hold time, SA8, SAD(7-0) valid after WR high	48		ns
tWHPH	td31	Delay time, WR high to CS high	21		ns
<sup>t</sup> RHPH	t <sub>d32</sub>	Delay time, RD high to CS high	21		ns
tPHPL	tw14	Pulse duration, CS high	21		ns

### subsystem Zilog-mode timing requirements (20 MHz) (see Figure 11)

ZILOG SYMBOL	JEDEC SYMBOL		MIN	MAX	UNIT
tdA(AS)	t <sub>su17</sub>	Setup time, SA8 and SAD(7-0) valid before $\overline{\text{AS}}$ high	20		ns
tdAS(A)	t <sub>d33</sub>	Delay time, $\overline{\text{AS}}$ high to SA8 and SAD(7–0) invalid	35		ns
tdAS(DR)	t <sub>d34</sub>	Delay time, $\overline{\text{AS}}$ high to data in on SAD(7–0)		150	ns
twAS	tw15	Pulse duration, AS low	35		ns
tdA(DS)	td35	Delay time, SA8 and SAD(7-0) invalid to DS low	0		ns
twDS(read)	tw16	Pulse duration, DS low (read)	125		ns
twDS(write)	tw17	Pulse duration, DS low (write)	65		ns
tdDS(DR)	td36	Delay time, DS low to data in valid		80	ns
thDS(DR)	t <sub>h17</sub>	Hold time, DS high to data in invalid	0		ns
tdDS(A)	t <sub>h18</sub>	Hold time, DS high to data out invalid	20		ns
tdDS(AS)	td37	Delay time, DS high to AS low	30		ns
tdDO(DS)	t <sub>d38</sub>	Delay time, SAD(7-0) (write data from μP) valid to DS low	10		ns
tdRW(AS)	t <sub>d</sub> 39	Delay time, R/W active to AS high	20		ns

SLLS225A - MARCH 1996 - REVISED FEBRUARY 1998

### subsystem Intel nonmultiplexed timing requirements (see Figure 12)

		MIN	MAX	UNIT
t <sub>su18</sub>	Setup time, SA(8−0), CS valid to RD, WR↓	30		ns
tw18	Pulse duration, RD low	120		ns
tw19	Pulse duration, WR low	120		ns
t <sub>su19</sub>	Setup time, SAD(7−0) valid to WR↑	50		ns
t <sub>en4</sub>	Enable time, $\overline{RD}\downarrow$ to SAD(7-0) driving	5		ns
t <sub>d40</sub>	Delay time, RD↓ to SAD(7-0) valid		105	ns
th19	Hold time, SA(8−0), CS valid after RD, WR↑	30		ns
th20	Hold time, SAD(7−0) valid after WR↑	30		ns
tdis3	Disable time, RD↑ to SAD(7-0) high impedance	5	15	ns

### subsystem Zilog nonmultiplexed timing requirments (see Figure 13)

		MIN	MAX	UNIT
t <sub>su20</sub>	Setup time, SA(8−0), CS, R/W valid to DS↓ (write)	90		ns
t <sub>su21</sub>	Setup time, SA(8−0), CS, R/W valid to DS↓ (read)	30		ns
t <sub>w20</sub>	Pulse duration, DS low (write)	65		ns
t <sub>w21</sub>	Pulse duration, DS low (read)	125		ns
t <sub>su22</sub>	Setup time, SAD(7−0) valid to DS↑	50		ns
t <sub>en5</sub>	Enable time, DS↓ to SAD(7-0) driving	5		ns
t <sub>d41</sub>	Delay time, DS↓ to SAD(7-0) valid		105	ns
th21	Hold time, SA(8−0), CS, R/W valid after DS↑	30		ns
t <sub>h22</sub>	Hold time, SAD(7−0), CS, R/W valid after DS↑	30		ns
<sup>t</sup> dis4	Hold time, DS↑ to SAD(7-0) high impedance	5	15	ns

SLLS225A - MARCH 1996 - REVISED FEBRUARY 1998

## ARBCLK switching characteristics over recommended operating free-air temperature range (see Figure 14)

	TES		NDITIONS	MIN	MAX	UNIT
t <sub>C4</sub>	Cycle time, internal arbitration clock ( ARBCLKI ÷ ARBPGM)	V <sub>CC</sub> = 3.3 V,	See Note 11	26	Note 14	20
		V <sub>CC</sub> = 5 V		14	Note 14	ns
t <sub>C5</sub>	Cycle time, arbitration clock	$V_{CC} = 3.3 \text{ V},$	See Note 11	26		ns
		$V_{CC} = 5 V$		14		113
t.140	Delay time, ARBCLKI↑ to ARBCLK0↑ (÷1)	$V_{CC} = 3.3 \text{ V},$	See Note 11		13	ns
td42		$V_{CC} = 5 V$			7.3	113
t <sub>d43</sub>	Delay time, ARBCLKI↓ to ARBCLK0↓ (÷1)	$V_{CC} = 3.3 \text{ V},$	See Note 11		15.5	20
		$V_{CC} = 5 V$			10	ns
	Delay time, ARBCLKI↑ to ARBCLK0↑ (÷2)	$V_{CC} = 3.3 \text{ V},$	See Note 11		15.3	ns
<sup>t</sup> d44		$V_{CC} = 5 V$			8.8	115
t.145	Delay time, ARBCLKI↑ to ARBCLK0↓ (÷2)	$V_{CC} = 3.3 \text{ V},$	See Note 11		17.5	ns
<sup>t</sup> d45		$V_{CC} = 5 V$			11	115
+	Delay time, ARBCLKI↑ to ARBCLK0↑ (÷4)	$V_{CC} = 3.3 \text{ V},$	See Note 11		19.5	ns
td46		$V_{CC} = 5 V$			11.5	118
+	Delay time, ARBCLKI↑ to ARBCLK0↓ (÷4)	$V_{CC} = 3.3 \text{ V},$	See Note 11		21.5	ns
td47		$V_{CC} = 5 V$			13.5	115
t 140	Delay time, ARBCLKI↑ to ARBCLK0↑ (÷8)	$V_{CC} = 3.3 \text{ V},$	See Note 11		22.7	ns
t <sub>d48</sub>		$V_{CC} = 5 V$			13.5	113
t-140	Delay time, ARBCLKI↑ to ARBCLK0↓ (÷8)	$V_{CC} = 3.3 \text{ V},$	See Note 11		25	ns
t <sub>d49</sub>		V <sub>CC</sub> = 5 V			15.7	113

NOTES: 11. TL16PC564BLV device tested at 3 V.

## reset timing requirements over recommended ranges of operating free-air temperature and supply voltage (unless otherwise noted) (see Figure 15)

		TEST CONDITIONS		MIN	MAX	UNIT
t <sub>w22</sub>	Pulse duration, RESET active			8⋅t <sub>c5</sub>		ns
t <sub>w23</sub>	Pulse duration, RESET inactive			8⋅t <sub>c5</sub>		ns
td50	Delay time, ARBCLKI↑ to RST low	$V_{CC} = 3.3 \text{ V},$	See Note 11		10.4	nc
		V <sub>CC</sub> = 5 V			7.5	ns
<sup>t</sup> d51	Delay time, ARBCLKI↑ to RST high impedance	$V_{CC} = 3.3 \text{ V},$	See Note 11		13.9	ne
		V <sub>CC</sub> = 5 V			9.7	ns

NOTE 11: TL16PC564BLV device tested at 3 V.

## subsystem interrupt-request timing requirements over recommended ranges of operating free-air temperature and supply voltage (see Figure 16)

		MIN	MAX	UNIT
t <sub>d52</sub>	Delay time, WE↑ to IRQ↑ (see Note 15)	2t <sub>C5</sub>	3t <sub>C5</sub>	ARBCLKI cycles
t <sub>d53</sub>	Delay time, SCR bit 6↑ to IRQ↓ (see Note 16)	t <sub>c5</sub>	2t <sub>C5</sub>	ARBCLKI cycles

NOTES: 11. TL16PC564BLV device tested at 3 V.

15. Synchronized to rising edge of ARBCLKI

16. Synchronized to falling edge of ARBCLKI



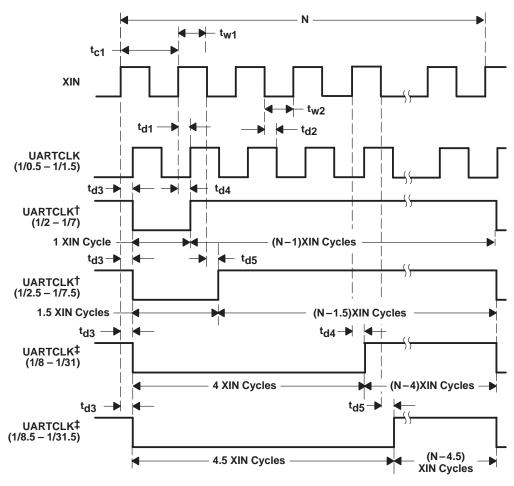
<sup>14.</sup> t<sub>C4</sub> MAX = N/6, where N = shortest (in ns) of the two attribute-memory accesses, host CPU or subsystem.

## host CPU status change timing requirements over recommended ranges of operating free-air temperature and supply voltage (see Figure 17)

		MIN	MAX	UNIT
t <sub>d54</sub>	Delay time, subsystem write↑ to STSCHG↓ (see Note 14)	2t <sub>C5</sub>	3t <sub>C5</sub>	ARBCLKI cycles
t <sub>d55</sub>	Delay time, OE↓ to STSCHG high impedance (see Note 15)	t <sub>c5</sub>	2t <sub>C5</sub>	ARBCLKI cycles

NOTES: 15. Synchronized to rising edge of ARBCLKI

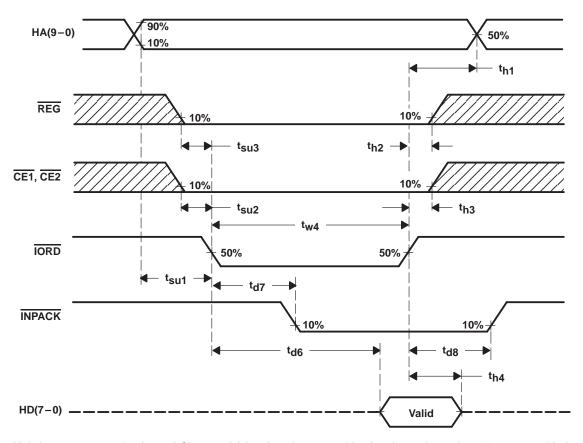
16. Synchronized to falling edge of ARBCLKI



<sup>†</sup> The low portion of the UARTCLK cycle = 1 XIN cycle for PGMCLK integer values of 2 to 7 and 1.5 XIN cycles for PGMCLK noninteger values 2.5 to 7.5.

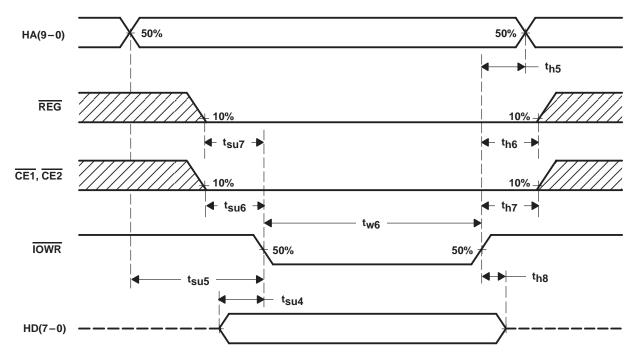
**Figure 1. XIN Clock Timing Waveforms** 

<sup>&</sup>lt;sup>‡</sup> The low portion of the UARTCLK cycle = 4 XIN cycles for PGMCLK integer values of 8 to 31 and 4.5 XIN cycles for PGMCLK noninteger values 8.5 to 31.5.



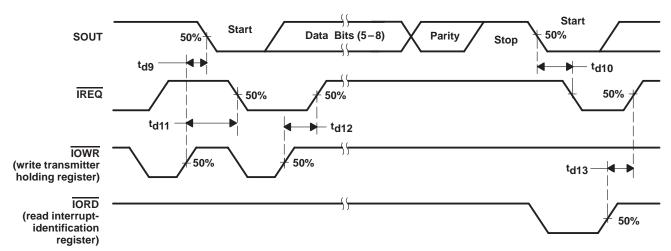
NOTE A: All timings are measured at the card. Skews and delays from the system driver/receiver to the card must be accounted for by the system design.

Figure 2. Host CPU I/O Read Timing Waveforms



NOTE A: All timings are measured at the card. Skews and delays from the system driver/receiver to the card must be accounted for by the system design.

Figure 3. Host CPU I/O Write Timing Waveforms



**Figure 4. Transmitter Timing Waveforms** 

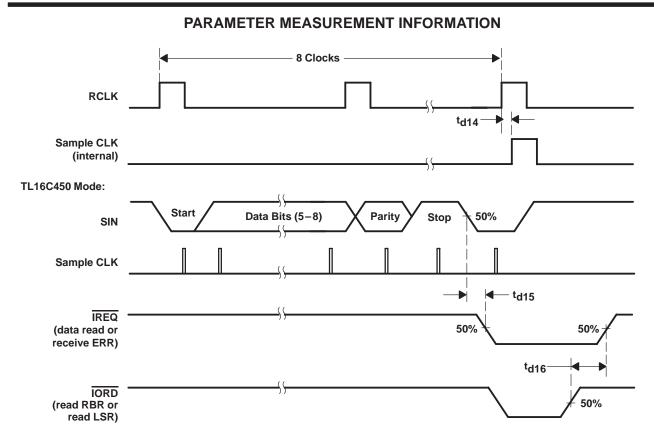
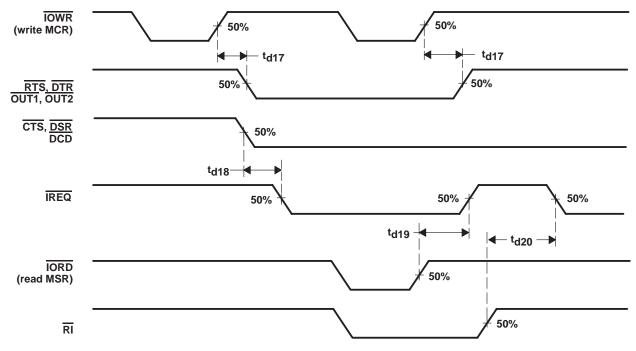
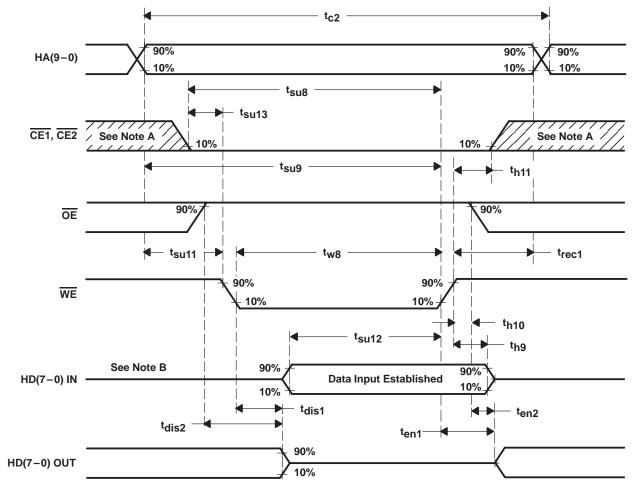


Figure 5. Receiver Timing Waveforms



**Figure 6. Modem Control Timing Waveforms** 



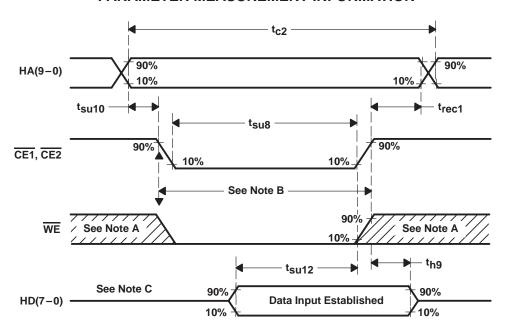


NOTES: A. The hatched portion may be either high or low.

B. When the data I/O terminal is in the output state, no signals should be applied to HD(7-0) by the system.

Figure 7. Host CPU Attribute-Memory Write Timing Waveforms (WE Control)

### PARAMETER MEASUREMENT INFORMATION

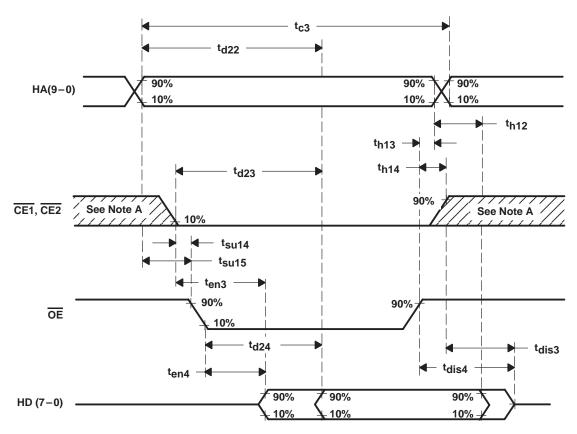


NOTES: A. The hatched portion may be either high (H) or low (L).

B. OE must be high (H).

C. When the data I/O terminal is in the output state, no signals should be applied to HD(7-0) by the system.

Figure 8. Host CPU Attribute-Memory Write Timing Waveforms (CE Control)



NOTE A: The shaded portion may be either high or low.

Figure 9. Host CPU Attribute-Memory Read Timing Waveforms

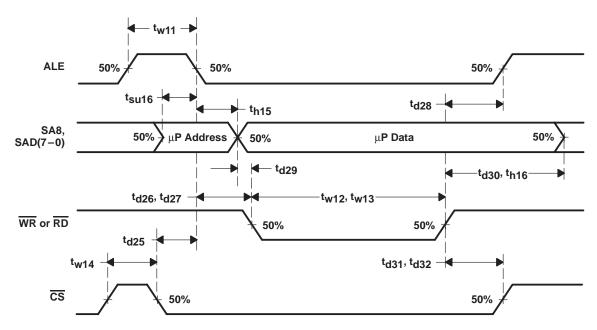
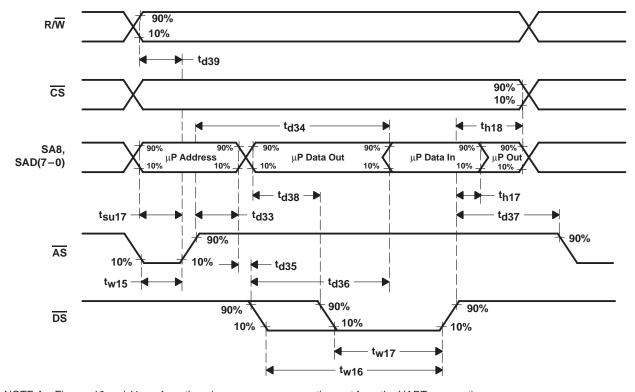


Figure 10. Subsystem Intel-Mode Timing Waveforms



NOTE A: Figures 10 and 11 are from the microprocessor perspective, not from the UART perspective.

Figure 11. Subsystem Zilog-Mode Timing Waveforms



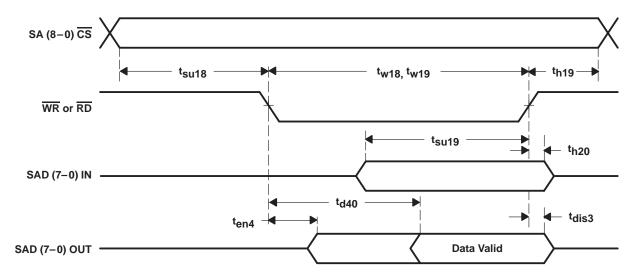


Figure 12. Subsystem Intel Nonmultiplexed Timing Waveforms

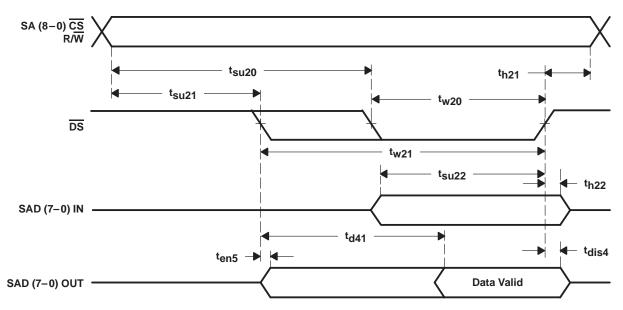


Figure 13. Subsystem Zilog Nonmultiplexed Timing Waveforms

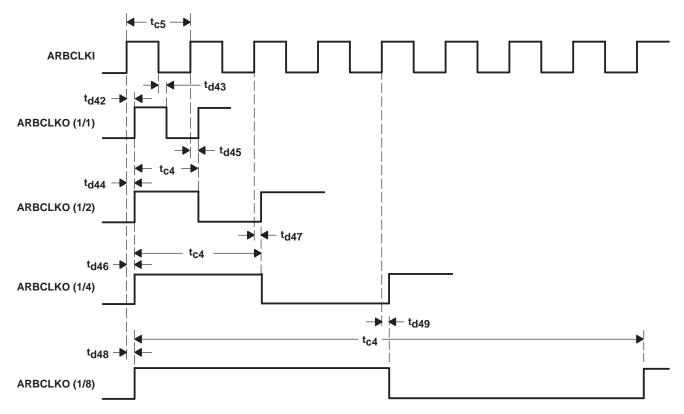
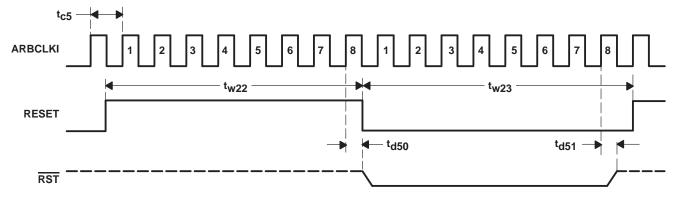


Figure 14. Arbitration-Clock Timing Waveforms



**Figure 15. Reset Timing Waveforms** 

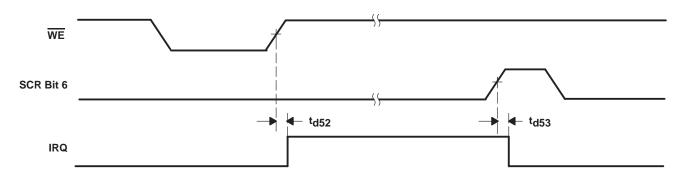


Figure 16. IRQ Timing Waveforms

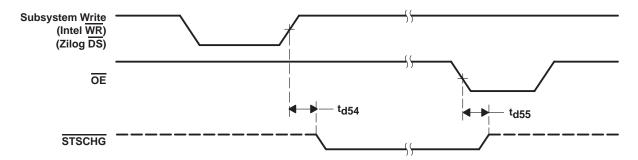
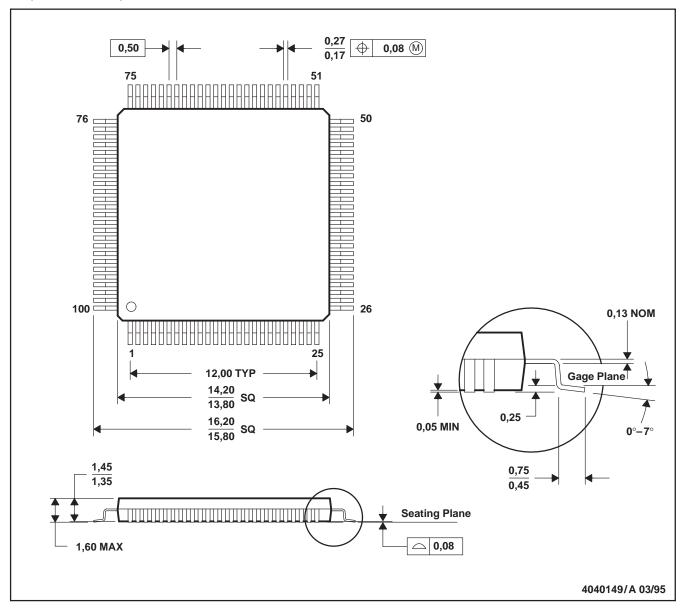


Figure 17. STSCHG Timing Waveforms

### **MECHANICAL DATA**

### PZ (S-PQFP-G100)

### PLASTIC QUAD FLATPACK



NOTES: A. All linear dimensions are in millimeters.

B. This drawing is subject to change without notice.

C. Falls within JEDEC MO-136

#### **IMPORTANT NOTICE**

Texas Instruments (TI) reserves the right to make changes to its products or to discontinue any semiconductor product or service without notice, and advises its customers to obtain the latest version of relevant information to verify, before placing orders, that the information being relied on is current and complete.

TI warrants performance of its semiconductor products and related software to the specifications applicable at the time of sale in accordance with TI's standard warranty. Testing and other quality control techniques are utilized to the extent TI deems necessary to support this warranty. Specific testing of all parameters of each device is not necessarily performed, except those mandated by government requirements.

Certain applications using semiconductor products may involve potential risks of death, personal injury, or severe property or environmental damage ("Critical Applications").

TI SEMICONDUCTOR PRODUCTS ARE NOT DESIGNED, INTENDED, AUTHORIZED, OR WARRANTED TO BE SUITABLE FOR USE IN LIFE-SUPPORT APPLICATIONS, DEVICES OR SYSTEMS OR OTHER CRITICAL APPLICATIONS.

Inclusion of TI products in such applications is understood to be fully at the risk of the customer. Use of TI products in such applications requires the written approval of an appropriate TI officer. Questions concerning potential risk applications should be directed to TI through a local SC sales office.

In order to minimize risks associated with the customer's applications, adequate design and operating safeguards should be provided by the customer to minimize inherent or procedural hazards.

TI assumes no liability for applications assistance, customer product design, software performance, or infringement of patents or services described herein. Nor does TI warrant or represent that any license, either express or implied, is granted under any patent right, copyright, mask work right, or other intellectual property right of TI covering or relating to any combination, machine, or process in which such semiconductor products or services might be or are used.

Copyright © 1998, Texas Instruments Incorporated